# Anisotropic Conductive Film (ACF) for Film On Board / Film for alternative to connector & solder

Products Category : Anisotropic Conductive Film (ACF)

Suitable for connection of rigid board and film material or connection between film materials.

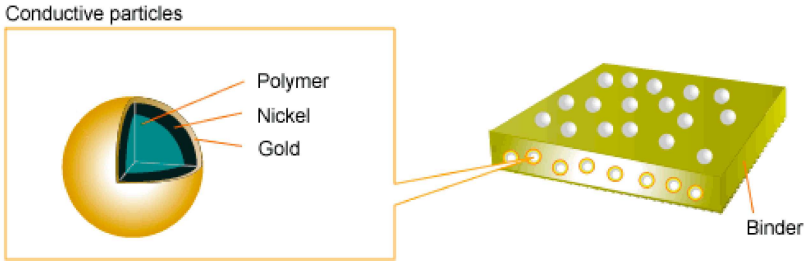
Please select the product name :

Comparison

CP801AM-35AC | **DP3342MS** | CP901AH-35AC

- **Product name** | DP3342MS
- **Suitable use** | For alternative to connector and solder
- **Application** | Computers/ AV/ Cellular phones
- **Features**
  - ACF interconnect offers cost reduction by replacing conventional mechanical connectors or soldering interconnect.
  - ACF interconnect allows low height and fine pitch which enables high density and miniaturizing of assembly.
  - Bonding at low temperature(130°C to 160°C). Suitable for repair.

## Structure



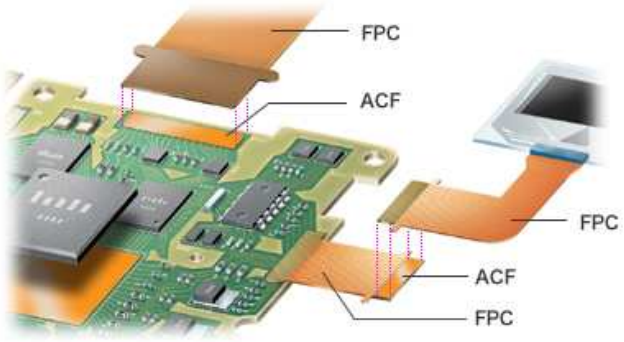

## Specifications

| | | |
|---|---|---|
| Product Name | | DP3342MS |
| Type | | FOB/FOF |
| Connection material | | FPC |
| | | PWB/FPC |
| Minimum space (μm) *1 | | 100 |
| Minimum pitch (μm) *2 | | 200 |
| Minimum connection area ($\mu m^2$) *3 | | - |
| Thickness (μm) | | 35 |
| Conductive particles | Type | Au/Ni plating on a polymer core particle |
| | Particle diameter (μmΦ) | 10 |
| | Insulation coated particle | NO |
| ACF Laminating conditions | Temperature (°C) *4 | 40 to 50 |
| | Time (sec) *5 | 1 to 2 |
| | Pressure (MPa) *6 | 0.5 to 1.5 |
| Main bonding conditions | Temperature (°C) *4 | 130 to 160 |
| | Time (sec) *5 | 6 |
| | Pressure (MPa) *7 | 1 to 4 |

*1 Minimum space: Space between neighboring circuits.
*2 Minimum pitch: Total length of conductor width and space between neighboring circuits.
*3 Minimum connection area: A contact area which needs to trap at least three particles (average -4.5δ) and where the faced conductor overlaps.
*4 Temperature of ACF lamination and main bonding: It is not equipment temperature, but temperature of ACF.
*5 Time of ACF lamination and main bonding: Time from the start of bonding to the point where the temperature reaches the target.
*6 Pressure of ACF lamination: It is described as the area of ACF lamination.
*7 Pressure of main bonding: The pressure at COG mounting is described as the total area of bumps. The pressure at FOG, FOB, and FOF mounting is described as the bonding area.

## Application Example

Replacing connectors / soldering interconnect.

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Note on the characteristic data given - Data on the characteristics of the products described in this page based on the results of evaluations carried out by the company. This does not guarantee that the characteristics of the product conform with your usage environment. Before use, review the usage conditions based on evaluation data obtained from the equipment and substrates actually used.